General Purpose Low Resistance Thick Film Chip Resistors

Version. C



FEATURE

- · High reliability.
- Low resistance value down to $10m\Omega$.
- RoHS complaint.
- Compatible with reflow and wave soldering type
- Applications:
 - Home appliances
 - Computer, notebook, workstation, tablet and peripherals
 - Instruments and meters
 - etc.

MANUFACTURER PART NO.

For example: GR1206J0R01T5G00 - GR1206 $\pm 5\%$ 10m Ω T/R-5000

Series	Size	Tol.	Nominal Resistance Value	PKG	SPQ	Feature	TCR
2 codes	4 codes	1 code	2~5 codes	1 code	1 code	1 code	2 codes
GR	1206	F	0R01	Т	5	G	00
General Purpose Low Resistance Thick Film Chip Resistors	0402 0603 0805 1206 1210 2010 2512	F=±1% J=±5%	0R01 ⁵ =0.01Ω, 10mΩ 0R47=0.47Ω, 470mΩ	T=T/R [®]	4=4K 5=5K	G=Std. S=P.C. [®]	00=Refer to table as below.

Note: ① R=Radix, 10^{0} , Ω

2 T/R=Taping in Reel package type

③ P.C.=Personal and Customized.

CHARACTERISTICS

Type	Rated Power	$MWV^{^{\scriptsize\textcircled{\scriptsize1}}}$	MOV ²	MRC [®]	MOC [®]	Tolerance	Value Range
GR0402	1/16W	50V	100V	0.79A	1.98A	±1%/±5%	100mΩ≦ R < 1000mΩ
GR0603	1/10W	75V	150V	3.16A	7.90A	±1%/±5%	10mΩ≦ R < 1000mΩ
GR0805	1/8W	150V	300V	1.10A	2.79A	±1%/±5%	100mΩ≦ R < 1000mΩ
	1/4W	150V	300V	5.00A	12.50A	±1%/±5%	10mΩ≦ R < 100mΩ
GR1206	1/4W	200V	400V	1.58A	3.95A	±1%/±5%	100mΩ≦ R < 1000mΩ
	1/3W	200V	400V	5.77A	14.43A	±1%/±5%	10mΩ≦ R < 100mΩ
GR1210	1/2W	200V	500V	7.07A	17.67A	±1%/±5%	10mΩ≦ R < 1000mΩ
GR2010	3/4W	200V	500V	8.66A	21.65A	±1%/±5%	10mΩ≦ R < 1000mΩ
GR2512	1W	200V	500V	10.00A	25.00A	±1%/±5%	10mΩ≦ R < 1000mΩ

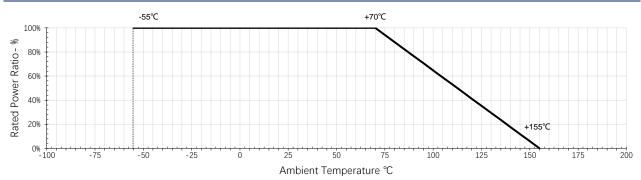
Note: 1 MWV=Max. Working Voltage.

2 MOV=Max. Overload Voltage.

③MRC=Max. Rated Current.

4 MOC=Max. Overload Current.

POWER DERATING CURVE



Note: Operating temperature range is from -55°C to +155°C

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RATED VOLTAGE

The resistor shall have a Rated Current which would be DC or AC corresponding to the Rated Power, and it can be calculated by formula as below.

The Rated Current of certain resistance value should be the calculated result or Max. Working Current of product series whichever less.

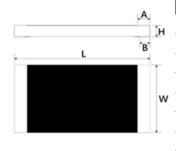
Formula:

$$I = \sqrt{P/R}$$

I=Rated current (A)
P=Rated power (W)
R=Nominal resistance (Ω)

DIMENSIONS

Unit: mm



Series	L	W	н	Α	В
GR0402	1.00±0.10	0.50±0.05	0.35±0.05	0.20±0.10	0.25±0.10
GR0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.20	0.30±0.20
GR0805	2.00±0.15	1.25±0.15	0.55±0.10	0.40±0.20	0.40±0.20
GR1206	3.10±0.15	1.55±0.15	0.55±0.10	0.45±0.20	0.45±0.20
GR1210	3.10±0.10	2.60±0.20	0.55±0.10	0.50±0.25	0.50±0.20
GR2010	5.00±0.10	2.50±0.20	0.55±0.10	0.60±0.25	0.50±0.20
GR2512	6.35±0.10	3.20±0.20	0.55±0.10	0.60±0.25	0.50±0.20

RELIABILITY

ltem	Test Method	Acceptable criterion
Temperature Coefficient of Resistance (T.C.R.)	$TCR(PPM/^{\circ}C) = \frac{(R_2 - R_1)}{R_1 \times (T_2 - T_1)} \times 10^6$ $R_1 = \text{Value in room temperature}$ $R_2 = \text{Value in test temperature} - 55^{\circ}C \text{ or } + 125^{\circ}C$ $T_1 = \text{Room temperature}$ $T_2 = \text{Test temperature} - 55^{\circ}C \text{ or } + 125^{\circ}C$ $Reference: IEC 60115 - 1 6.2$	0402: $100mΩ ≤ R < 1000mΩ: ±1000PPM/°C$ 0603: $10mΩ ≤ R ≤ 30mΩ: ±1500PPM/°C$ $30mΩ < R ≤ 50mΩ: ±1000PPM/°C$ $50mΩ < R < 1000mΩ: ±800PPM/°C$ 0805, 1206, 1210, 2010, 2512: $10mΩ ≤ R ≤ 15mΩ: ±1500PPM/°C$ $15mΩ < R ≤ 30mΩ: ±1000PPM/°C$ $30mΩ < R < 1000mΩ: ±800PPM/°C$
Insulation Resistance	Using the parallel clamp method: $100\pm15V_{\text{DC}}$ voltage is applied between the electrode and the substrate within 60 seconds. Test the insulation resistance between the terminal and the back of the part. Reference: IEC 60115-1 12.1.3.5	$\geq 10^9 \Omega$
Dielectric Withstanding Voltage	An alternating current with an effective value of the maximum overload voltage is applied between the electrode and the substrate at a rate of approximately 100V/sec. Pressure, maintain 60± 5 sec. The test voltage reference to the DWV in characteristics. Reference: IEC 60115-1 12.2.4	Test to confirm if the presence of current or arc breakdown by ≥10uA
Short Time Over Load	Apply 2.5 times of rated voltage or maximum overload voltage (whichever is the smallest) for 5 seconds Reference: IEC 60115-1 8.1.4.2	1% series: △R/R=±1.0% 5% series: △R/R=±2.0%
Intermittent Overload	Put it in the thermostat, apply 2.5 times of rated voltage, 1 second ON, 25 seconds OFF, 10000 ⁺⁴⁰⁰ ₋₀ cycles, take it out and stand for 60 minutes, then measure the change rate of resistance value. Reference: IEC 60115-1 8.4.4	△R/R=±5.0%
Resistance to Solvent	Immerse in isopropanol solvent at room temperature (23±5°C) for 5min, wipe 10 times with a hard toothbrush, repeat 3 times, take out and blow dry for examination Reference: IEC 60115-1 11.3.2 method1	No obvious damage, peeling, swelling phenomenon

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Item	Test Metho	od					Acceptable criterion
Solderability	Pretreatment: dry heat 155°C, 4 hrs. or PCT aging for 4 hrs. (equivalent), after take out, stand at room temperature for 2 hrs. Test method: 1. Dip the resistance in a tin furnace at 245±3°C for 3 seconds, then take it out and observe the solder area under a microscope; 2. Reflow soldering test, Peak Temperature: 235°C, T=40±5 sec. Reference: IEC 60115-1 11.1.4.3						Solder coverage over 95% No welding refusal phenomenon, si soldering height is greater than 1/2 of theight
Leaching	stand at ro dip in a tin Observe th	ent: 55°C, 4 hrs. or som temperatu furnace at 26 ne area of sold IEC-60068-2	ure for 2 h 0 ^{±5} °C for ler under a	No electrode is eroded to expose the substrate phenomenon			
Resistance to Soldering Heat	The tested resistor be immersed into molten solder of $260^{+5}_{-0}^{\circ}$ C for 10 seconds. Then the resistor is left in the room for 1 hr., then measure the change rate of resistance value Reference: IEC 60115-1 11.2.4.3						△R/R=±1.0%
Thermal Shock	High and low temperature test is carried out according to the upper and lower limits of the application temperature of the parts, the residence time of the upper and lower limits of the temperature is 30min, and the temperature conversion time is less than 30s, lasting 500 cycles Reference: IEC 60115-1 10.1.4						△R/R=±1.0%
Solder Joint Endurance Test	The SMD resistance was welded to the test board and bent with the standard pressure block. After standing for 60 sec. under the corresponding deformation condition, the change rate of resistance value of the part was tested. Size 0402, 0603, 0805 1206, 1210 2010, 2512 Depth 5mm 3mm 2mm					△R/R=±1.0%	
Resistance to Dry Heat	Put it in an oven at 155±5°C for 1000 ⁴⁸ ₋₀ hrs., take it out and let it stand for more than 1hr., then measure the change rate of resistance value Reference: IEC 60115-1 7.3						1% series: \triangle R/R=±1.0% 5% series: \triangle R/R=±3.0%
Loading Life in Moisture	Place it in a constant temperature and humidity box with 40±2°C and 90~95%RH and apply the rated voltage with 90 minutes ON and 30 minutes OFF, 1000 hrs. Take it out and stand for 60 minutes, and then measure the change rate Reference: IEC 60115-1 10.4						1% series: △R/R=±1.0% 5% series: △R/R=±3.0%
Load Life	Put in an oven at $70\pm2^{\circ}$ C, apply rated voltage, 90 min ON, 30 min OFF, 1000 hrs., take out and stand for more than 60 min, then measure the resistance change rate. Reference: IEC 60115-1 7.1						
Low temperature load test	-55°C, unpowered, 1 hr.: Rated voltage/current for 45 minutes, then unpowered within 15 minutes, return to room temperature, take out and stand for 24 hours, then measure the change rate of resistance value. Reference: IEC 60115-1 10.2.4						1% series: \triangle R/R=±1.0% 5% series: \triangle R/R=±2.0%
Shear force test	Weld the part to the PCB. Apply the corresponding test stress from the side of the part with the test terminal for 10s. Check the appearance of the welded end of the part under the stress condition Size 0402, 0603 0805 1206, 1210 2010, 2512 Test force 5N 9N 25N 45N Reference: IEC 60115-1 9.7						

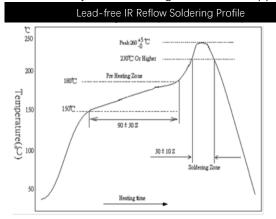
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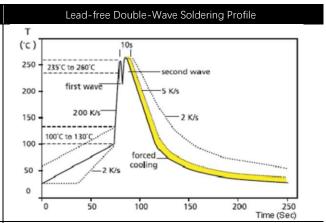
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SOLDERING TEMPERATURE

- Recommendation only.
- Please adjust it according to the actual application





Note:

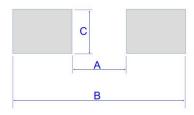
- The Max. Temp. is 260+5/-0°C within 10 sec
- · Reference: J-STD-020D

Note:

- Suit for ≥ 0603 size
- Manual soldering in 350±10°C within 3 sec

SOLDERING PAD

Resistance value would be lower than nominal value because of joint with soldering material, so designing circuit should adjust the pad size



			Unit: mm
Type	А	В	С
GR0402	0.5	1.5	0.6
GR0603	0.8	2.1	0.9
GR0805	1.2	3.0	1.3
GR1206	2.2	4.2	1.6
GR1210	2.2	4.2	2.8
GR2010	3.5	6.1	2.8
GR2512	3.8	8.0	3.5

WORKING ENVIRONMENT

If user intends to use products in special environments or states (including but not limited to the following), it is necessary to approve special characteristics and reliability for the following or other application environments.

- A. High temperature, high moisture.
- B. Near the sea, or corrosive gas, such as Cl₂, H₂S, NH₃, SO₂ and NO₂, etc.
- C. Unverified liquids, such as water, oil, chemical or organic solvent.
- D. Unverified resin or paint to cover products.
- E. Products should be washed with water soluble cleaner even if non cleaning flux.

STORAGE / CARRY CONDITIONS

A. Temperature: 25±5℃
B. Humidity: 60±15%RH
C. Storage life: 2 years. FIFO

D. Please hold box correct orientation when storing and carrying. It is strictly prohibited to fall or squeeze the box, otherwise the product electrode or body may be damaged.

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VERSION HISTORY

Version	Date	Change Item(s)	Description
А	2022/05/25	-	First version
В	2022/12/07	Reliability	Update test items, test method and acceptable criterion.
С	2023/03/03	Characteristics	① Remarked MWV and MOV. ② Added 0402 size.
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